Amendments to the Specification:

Please amend the specification as follows:

Page 6 paragraph starting at line 17 ending at line 27

A1

An optical section 36 is provided in an elevated position relative to the chuck 32. An exposure light radiation section (not shown) for radiating exposure light of predetermined width to the edge of the semiconductor wafer 34 is provided at a lower end of the optical section 36. In the wafer edge exposure apparatus according to the present embodiment, exposure light 50 can be radiated onto the edge of the semiconductor wafer 34; more specifically, an annular portion of predetermined width located at the outermost edge of the semiconductor wafer 34, by means of rotating the chuck drive motor 30 under circumstances where the optical section 36 produces exposure light 50.

Page 8 paragraph starting at line 9 ending at line 17

A2

Next, the optical section 36 produces exposure light 50, and the chuck drive motor 30 is rotated, whereby there is performed processing for exposing the edge of the semiconductor wafer 34 (step 124). As a result of exposure processing being performed, the resist on the semiconductor wafer 34 is exposed under optimum focusing conditions. Accordingly, when development processing (step 108 shown in Fig. 3) is performed, the resist on the semiconductor wafer 34 is patterned such that the end face of the resist becomes substantially perpendicular.